

N728-LA

Product Specifications

Cat.4 Module Issue 1.0 Date 2023-08-04





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This document is intended for system engineers (SEs), development engineers, and test engineers.

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This device complies with Part 15 of the FCC Rules. Operation is subject to the following two conditions:

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Contents

1 Safety Recommendations	8
2 About N728-LA	9
2.1 Product Overview	9
2.2 Block Diagram	10
2.3 Basic Features	10
3 Reference Standard	
4 RF Interface Designs	13
4.1.1 ANT_MAIN/ANT_DIV Antenna Interfaces	
4.1.2 ANT_GNSS Antenna Interface	
4.1.3 Antenna Assembling	
5 Electrical Characteristics and Reliability	21
5.1 Electrical Characteristics	
5.2 Temperature Characteristics	21
5.3 ESD Protection Characteristics	22
6 RF Characteristics	23
6.1 Operating Frequency Bands	23
6.2 TX Power and RX Sensitivity	24
6.3 GNSS Technical Parameters	26
7 Considerations for N728-LA Module Usage	27
8 Mechanical Characteristics	28
8.1 Dimensions	28
8.2 Labeling	29
8.3 Packaging	29
8.3.1 Tray	29
8.3.2 Moisture Sensitivity Level	30
9 Mounting N728-LA onto Application Board	31
9.1 PCB Package	31
9.2 Stencil	31
9.3 Solder Paste	32
9.4 Oven Temperature Profile	32
A Abbreviations	34



Table of Figures

Figure 5-1 L-type RF matching schematics	13
Figure 5-2 T-type RF matching schematics	14
Figure 5-3 π-type RF matching schematics	14
Figure 5-4 Recommended RF PCB design	15
Figure 5-5 GNSS RF structure	15
Figure 5-6 Reference design of active GNSS antenna 11	16
Figure 5-7 Reference design of active GNSS antenna 2	17
Figure 5-8 Reference design of passive GNSS antenna	18
Figure 5-9 Murata RF connector encapsulation specifications	
Figure 5-10 RF cable connections	19
Figure 5-11 Antenna layout	20
Figure 5-12 Layout around the antenna	20
Figure 9-1 N728-LA top and side view dimensions (unit: mm)	28
Figure 9-2 N728-LA packaging	30
Figure 10-1 Bottom view of N728-LA PCB package (unit: mm)	31
Figure 10-2 Oven temperature profile	32



Table of Tables

Table 2-1 Supported frequency bands	9
Table 6-1 N728-LA electrical characteristics	21
Table 6-2 N728-LA temperature characteristics	21
Table 6-3 N728-LA ESD protection characteristics	22
Table 7-1 N728-LA operating bands	23
Table 7-2 N728-LA RF transmitting power	24
Table 7-3 N728-LA GSM RX sensitivity	25
Table 7-4 N728-LA WCDMA RX sensitivity	25
Table 7-5 N728-LA LTE RX sensitivity	25
Table 7-6 GNSS technical parameters	26



About This Document

Scope

This document is applicable to N728-LA.

Audience

This document is intended for system engineers (SEs), development engineers, and test engineers.

Change History

Issue	Date	Change	Changed By
1.0	2023-05	Initial draft	Zou Shiqiang

Conventions

Symbol	Indication
0	This warning symbol means danger. You are in a situation that could cause fatal device damage or even bodily damage.
!	Means reader be careful. In this situation, you might perform an action that could result in module or product damages.
•	Means note or tips for readers to use the module



1 Safety Recommendations

Please read carefully and strictly adhere to the following safety recommendations to ensure that the product complies with national and environmental requirements, and to avoid potential threats to personal safety and protect the product and work environment from damage:

- Do not use in areas where there is a risk of fire or explosion.
 Using the product in areas with flammable gases, such as propane, gasoline, or combustible sprays, or dust, can result in explosions or fires.
- In places where wireless communication is prohibited, please turn off the wireless communication function.

If the product is used in medical institutions or on airplanes, electromagnetic waves emitted by this product may interfere with surrounding equipment.

Follow the requirements below in design and use of the application for this module:

- Do not disassemble the product without authorization, otherwise, the product's after-sales warranty service cannot be provided.
- Please design the product correctly according to the Hardware User Guide. Please connect the
 product to a stable power supply voltage, and the wiring should comply with safety and fire
 prevention management requirements.
- Avoid touching the pins of the module directly in case of damages caused by ESD.
- Do not insert or remove the SIM card or mobile storage card while the product is not turned off.



2 About N728-LA

This chapter introduces product overview, block diagram, and basic features of N728-LA.

2.1 Product Overview

N728-LA is an industrial-grade cellular module that supports LTE-FDD, LTE-TDD, WCDMA, and GSM. Measuring (30.00 ± 0.10) mm × (28.00 ± 0.10) mm × (2.75 ± 0.20) mm, the module supports PHY chip with external RMII interface, WLAN chip with SDIO interface, and Codec chip with PCM / I2S interface. It is suitable for developing IoT communication devices such as wireless meter reading terminals, vehicle/handheld POS, industrial routers and so on.

N728-LA has the following features:

- ARM Cortex-R5 processor, with CPU clock speed up to 832 MHz, 32 KB L1 cache.
- Supported network modes: LTE Cat. 4, WCDMA, GSM.
- Supported interfaces: USIM, USB2.0, UART, I2C, I2S/PCM, SPI, SDIO, SDC, RMII, 1PPS, GPIO.

Table 2-1 lists the frequency bands that N728-LA supports.

Table 2-1 Supported frequency bands

Region	Category	Frequency band	GNSS ¹	Diversity antenna ²
Latin America	Cat4	FDD-LTE: B2, B4, B5, B7, B66 TDD-LTE: B38, B41 WCDMA: B2, B5 GSM/GPRS/EDGE: 850/1900 MHz	Supported	Not supported

Diversity antenna² indicates that the diversity antenna is an optional configuration.

GNSS¹ indicates that GNSS is an optional configuration.



2.2 Block Diagram

N728-LA consists of the following functionality units:

- Baseband chip
- 26 MHz crystal
- Power management
- Radio frequency unit
- Supported interfaces: USIM, USB2.0, UART, I2C, I2S/PCM, SPI, SDIO, SDC, RMII, 1PPS, GPIO.

2.3 Basic Features

Features	Description		
Physical features	 Dimensions: (30.00±0.10) mm × (28.00±0.10) mm × (2.75±0.20) mm Package: LGA Weight: about 5.10 g 		
Temperature ranges	Operating: -30°C to +75°C Extended ³ : -40°C to +85°C Storage: -40°C to +90°C		
Operating voltage	VBAT: 3.4 V to 4.2 V, typical value: 3.8 V		
	Sleep mode ⁴⁾ : ≤ 4.5 mA		
Operating current	Idle mode ⁵⁾ : ≤ 36 mA (GNSS disabled)		
	Operating mode ⁶⁾ (LTE mode): TBD		
Application processor	ARM Cortex-R5 processor, with CPU clock speed up to 832 MHz, 32 KB L1 cache		

Extended³: the module can be registered on the network, but some indicators cannot meet 3GPP standards.

Sleep mode⁴: means the current drawn by the module in sleep mode, a low power consumption state, in which its RF function is functioning properly but its peripheral interfaces are disabled. If there is an incoming call or SMS, the module will exit from the sleep mode, and after the incoming call or voice instant messaging has ended, the module will re-enter the sleep mode.

Idle mode⁵: means the current drawn by the module in a normal operating mode, but no data service is being processed.

Operating mode⁶: current drawn by the module while it is in the state of data communication.



Memory	RAM: 32 MB ROM: 16 MB
Band	See Table 2-1.
Wireless rate	GPRS: Max 85.6 kbps (DL)/Max 85.6 kbps (UL) EDGE: Max 236.8 kbps (DL)/Max 236.8 kbps (UL) WCDMA: HSPA+, Max 21 Mbps (DL)/Max 5.76 Mbps (UL) LTE-FDD: Cat4, With-DRX, Max 150 Mbps (DL)/Max 50 Mbps (UL) LTE-TDD: Cat4, With-DRX, Max 130 Mbps (DL)/Max 30 Mbps (UL) LTE-FDD: Cat4, Without-DRX, Max 75 Mbps (DL)/Max 50 Mbps (UL) LTE-TDD: Cat4, Without-DRX, Max 65 Mbps (DL)/Max 30 Mbps (UL)
Transmit power	EGSM900: +33 dBm (Power Class 4) DCS1800: +30 dBm (Power Class 1) EDGE 900 MHz: +27 dBm (Power Class E2) EDGE1800 MHz: +26 dBm (Power Class E2) WCDMA: +23 dBm (Power Class 3) LTE: +23 dBm (Power Class 3)
	2G/3G/4G antenna 4G diversity receiving antenna GNSS antenna, the characteristic impedance of each antenna is 50 Ω .
	One USIM interface, supporting 1.8 V/3.0 V USIM cards.
	One USB2.0 interface.
	Three UART (one of which is a Debug UART)
Application	One I2C interface, for master mode only
interfaces	One I2S / PCM interface
	One SPI interface, host mode only
	One SDIO interface, for WLAN
	One RMII interface
	One 1PPS interface
	GPIO interfaces
AT commands	3GPP Release 9 Neoway extended AT commands
SMS	PDU, TXT
Data	PPP, RNDIS
Protocol	TCP/TCPS, UDP, HTTP/HTTPS, FTP, MQTT
Authentication	TBD



3 Reference Standard

N728-LA is designed by referring to the following standards:

- 3GPP TS 36.521-1 V9.10.0 User Equipment (UE) conformance specification; Radio transmission and reception; Part 3: Radio Resource Management (RRM) conformance testing
- 3GPP TS 21.111 V9.0.0 USIM and IC card requirements
- 3GPP TS 31.102 V9.19.0 Characteristics of the Universal Subscriber Identity Module (USIM) application
- 3GPP TS 31.111 V9.12.2 Universal Subscriber Identity Module (USIM) Application Toolkit (USAT)
- 3GPP TS 27.007 V9.9.0 AT command set for User Equipment (UE)
- 3GPP TS 27.005 V9.0.1 Use of Data Terminal Equipment Data Circuit terminating Equipment (DTE - DCE) interface for Short Message Service (SMS) and Cell Broadcast Service (CBS)



4 RF Interface Designs

Signal	Pin SN	I/O	Function description	Remarks
ANT_MAIN	76	AI	2G/3G/4G main antenna pin	Requiring 50 Ω impedance
ANT_DIV	94	Al	4G diversity antenna pin	characteristic.
ANT_GNSS	92	-	GNSS antenna pin	

4.1.1 ANT_MAIN/ANT_DIV Antenna Interfaces

The MAIN/DIV antenna interface of the N728-LA module requires the 50Ω impedance characteristic. The impedance of the cable from the module interface to the antenna needs to be kept within the impedance range to ensure RF performance. Therefore, you should control the impedance of the traces between the pins and antenna to ensure the RF performance. An impedance matching circuit, such as the L network, split capacitor network, and pi network is mandatory in between. Pi network is recommended.

ANT_MAIN

Z2

Z1

Z1

Module

Figure 4-1 L-type RF matching schematics



ANT_MAIN

Z1

Z2

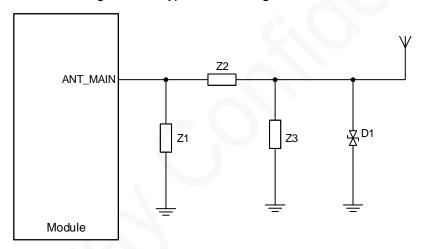
Z3

Z3

Module

Figure 4-2 T-type RF matching schematics





Schematic Design Guidelines

- Element components in the above figures are capacitors, inductors, and 0 Ω resistors. Place these RLC components as close to the antenna interface as possible.
- If static electricity may be introduced through the antenna, it is recommended to add TVS components with ultra-low junction capacitance for static electricity protection. TVS diodes with junction capacitance less than 0.5 pF are preferred. Besides, it is necessary to ensure that the reverse breakdown voltage of TVS diodes is greater than 10 V, and TVS diodes with reverse breakdown voltage above 15 V are preferred.

PCB Design Guidelines:

- Lay copper foil around the RF connector. Dig as many ground holes as possible on the copper and the characteristic impedance of all RF traces should be controlled to 50 Ω.
- Keep the traces as short as possible and control their characteristic impedance at 50 Ω



 To avoid antenna performance being affected significantly by the parasitic capacitance of a large RF pad when using SMA connector, remove the copper on the first and fourth layers or all layers of a multiple-layer PCB under the RF solder pad. The following is the recommended RF PCB design.

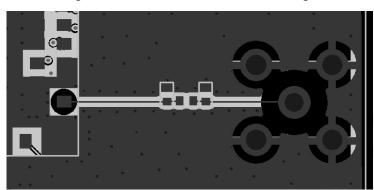


Figure 4-4 Recommended RF PCB design

- A reasonable distance should be kept between ANT_MAIN and ANT_DIV to avoid mutual interference that may affect reception performance.
- On the PCB, keep the RF signals and components far away from high-speed circuits, power supplies, transformers, great inductors, the clock, etc.

4.1.2 ANT_GNSS Antenna Interface

GNSS Impedance Control

ANT_GNSS (pin #92) is the GNSS antenna interface of the module, which requires a characteristic impedance of 50 Ω . The following shows the GNSS structure inside the module.

ANT_GNSS LNA Z2 SAW Z3 GNSS_RF_IN

Module

Figure 4-5 GNSS RF structure



Schematic Design Guidelines

- For the matching circuitry between the module interface and GNSS antenna, please refer to the schematic design in section 4.1.1 ANT_MAIN/ANT_DIV Antenna Interfaces.
- There is an LNA inside the module; if a passive GNSS antenna is adopted, do not add an LNA.

Reference design of active GNSS antenna

After the GNSS antenna receives GNSS satellite signals, the signals are amplified by the front LNA (Low Noise Amplifier) inside the active antenna and then sent to the ANT_GNSS pin of the module through the feeder and PCB traces. The following figure shows the reference design of the active GNSS antenna.

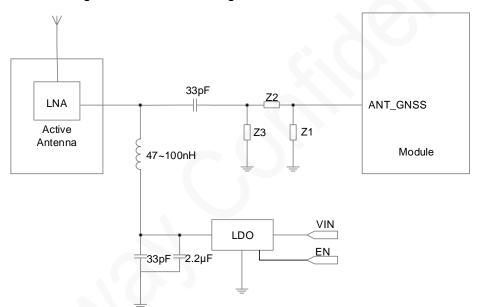


Figure 4-6 Reference design of active GNSS antenna 11



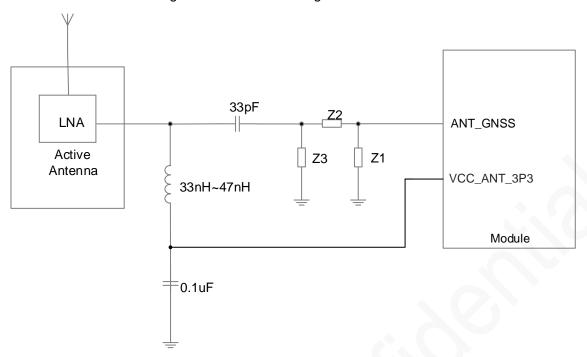


Figure 4-7 Reference design of active GNSS antenna 2

Schematic Design Guidelines

 If using an active GNSS antenna due to the presence of an LNA within the module, please verify the specifications of the active antenna with Neoway FAEs.

PCB Design Guidelines:

- For cautions of PCB design between GNSS interface and antenna, refer to the PCB design guidelines in section 4.1.1 ANT_MAIN/ANT_DIV Antenna Interfaces.
- 50 Ω impedance control is required for both antenna feeders and the PCB traces between the antenna interface and LNA, and the traces should not be too long. The power supply of the active antenna is fed via an inductor of 47 nH 100 nH from the signal line of the antenna.
- The common active antenna requires a 3.3 V to 5 V power supply. The active antenna itself
 consumes less power, but it requires LDO with a low noise coefficient to supply power to the
 antenna through an inductor of 100NH, as shown in the figure above.
- Keep the GNSS RF circuit away from the main and BT antenna circuits as far as possible on PCB. Otherwise, the RF performance may be affected.

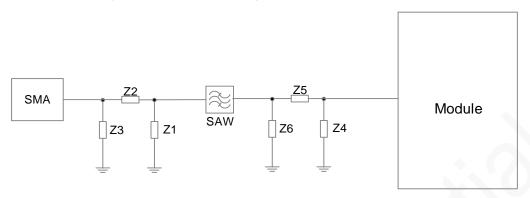
Reference design of passive GNSS antenna

After the GNSS antenna receives the GNSS satellite signal, it is transmitted to the ANT_GNSS pin of the N728-LA odule through the PCB traces. The following figure shows a reference design of the



passive GNSS antenna.

Figure 4-8 Reference design of passive GNSS antenna



Schematic Design Guidelines

• In general, when using a passive antenna, there is no need to add an external SAW filter. If there is significant interference around the GNSS antenna, it is recommended to add a SAW filter.

PCB Design Guidelines:

- For cautions of PCB design between the GNSS interface and the antenna, refer to the PCB design guidelines in 4.1.1.
- Keep the GNSS RF circuit away from the main and BT antenna circuits as far as possible on your application PCB. Otherwise, the RF performance may be affected.
- There is an LNA inside the module; if a passive GNSS antenna is adopted, do not add an LNA.

4.1.3 Antenna Assembling

The antenna used by the module must comply with the mobile device standard. The standing wave ratio should be between 1.1 and 1.5, and the input impedance should be 50 Ω . Requirements for antenna gain vary according to the application environment. In general, the greater the in-band gain and the smaller the out-of-band gain, the better the performance of the antenna.

Antenna interfaces can be connected to a rubber ducky antenna, magnet antenna, or embedded Planar Inverted F Antenna (PIFA). While using an external RF antenna, keep the external RF cables far away from all interference sources, especially digital signals and switching power supply.

The following methods are commonly used to assemble antennas:

Reference design for external antennas (GSC RF connector)
 MM9329-2700RA1 from Murata is recommended. The following figure shows its encapsulation specifications.



Figure 4-9 Murata RF connector encapsulation specifications

Connecting to an external antenna by soldering
 It is not recommended to solder the RF cables to the module directly since the stability, consistency, and RF performance are not good.

The following show the two types of connections.

Figure 4-10 RF cable connections



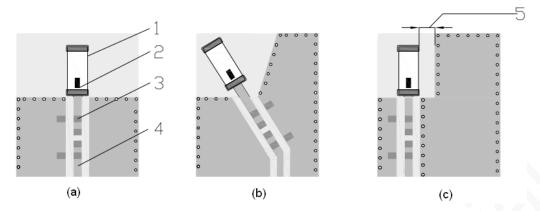
PCB printing or SMT

The module works in a wide frequency range, but it is difficult for PCB antennas or ceramic antennas to cover a wide frequency. Therefore, this connection method is recommended only for 2.4 GHz Wi-Fi or BT/ BLE antennas.

The following figure shows the layout of the 2.4 GHz ceramic chip antenna. SLDA52-2R540G-S1TF is used as an example.



Figure 4-11 Antenna layout



If your PCB is large enough, you can adopt the layout shown in Figure 4-11 (a).

- 1 Chip antenna
- 2 Feeding mark
- 3 Solder pad of the matching circuitry
- 4 50 Ω characteristic impedance RF trace

Figure 4-12 shows the layout for the area between the antenna and ground that is marked as "5" in Figure 4-11.

W=6.8mm
No Ground Area

Figure 4-12 Layout around the antenna

For more details, refer to the antenna manuals and other documents.



5 Electrical Characteristics and Reliability

5.1 Electrical Characteristics



- If the voltage is lower than the threshold, the module might fail to start. If the voltage is higher than threshold or there is a voltage burst during the startup, the module might be damaged permanently.
- If you use LDO or DC-DC to supply power for the module, ensure that it outputs at least 2.5 A current. The 2.5 A current corresponds to the maximum power level of the module at GSM mode, and the peak current during burst transmission lasts for a short time. Placing a large capacitor at the VBAT pin of the module can effectively enhance the freewheeling current of the power supply and avoid abnormalities such as module shutdown caused by excessive voltage drop.

Table 5-1 N728-LA electrical characteristics

Parameter		Minimum value	Typical value	Max. value
VBAT	V_{in}	3.4 V	3.8 V	4.2 V
VDAT	l _{in}	N/A	N/A	TBD
VBACKUP	V_{in}	1.4 V	3.3 V	3.6 V
VBACKUP	I _{in}	N/A	8uA	N/A

5.2 Temperature Characteristics

Table 5-2 N728-LA temperature characteristics

Parameter	Minimum value	Typical value	Max. value	
Operating	-30°C	25℃	75℃	
Extended	-40°C	25℃	85℃	
Storage	-40°C	25°C	90℃	





In the event that the temperature in the operating environment surpasses the designated thresholds, certain RF performance indicators of the module may deteriorate and fall short of the 3GPP specification requirements. However, despite this, the module's regular functionality will not be significantly affected. It is possible for the RF performance to return to the required 3GPP standards once the temperature is normalized.

5.3 ESD Protection Characteristics

To guarantee quality, electronic products are required to undergo comprehensive electrostatic discharge (ESD) testing. Therefore, it is crucial to take into account the electrostatic protection capabilities of the primary module pins during the design of related products. The following is the ESD protection characteristic data of this module. When designing related products, you need to add appropriate ESD protection according to the industry, depending on the industry in which the product will be used to prevent damage and ensure optimal performance.

Test environment: humidity 45%; temperature 25℃

Table 5-3 N728-LA ESD protection characteristics

Contact point	Contact discharge	Air discharge
GND	±8 kV	±15 kV
ANT	±8 kV	±15 kV
Shielding cover	±8 kV	±15 kV



6 RF Characteristics

N728-LA provides connectivity on GSM, WCDMA, FDD-LTE, TDD-LTE (Cat4) networks. This chapter introduces the RF characteristics of N728-LA.

6.1 Operating Frequency Bands

Table 6-1 N728-LA operating bands

Operating bands	Uplink	Downlink
GSM850	824.2 - 848.8 MHz	869.2 - 893.8 MHz
EGSM900	880 - 915 MHz	925 - 960 MHz
DCS1800	1710 - 1785 MHz	1805 - 1880 MHz
PCS1900	1850.2 - 1909.8 MHz	1930.2 - 1989.8 MHz
WCDMA B1	1920 - 1980 MHz	2110 - 2170 MHz
WCDMA B2	1852.4 - 1907.6 MHz	1932.4 - 1987.6 MHz
WCDMA B4	1712.4 - 1752.6 MHz	2112.4 - 2152.6 MHz
WCDMA B5	824 - 849 MHz	869 - 894 MHz
WCDMA B8	880 - 915 MHz	925 - 960 MHz
LTE-FDD B1	1920 - 1980 MHz	2110 - 2170 MHz
LTE-FDD B2	1850 - 1910 MHz	1930 - 1990 MHz
LTE-FDD B1	1710 - 1785 MHz	1805 - 1880 MHz
LTE-FDD B4	1710 - 1755 MHz	2110 - 2155 MHz
LTE-FDD B5	824 - 849 MHz	869 - 894 MHz
LTE-FDD B7	2500 - 2570 MHz	2620 - 2690 MHz
LTE-FDD B8	880 - 915 MHz	925 - 960 MHz
LTE-FDD B10	1710 - 1770 MHz	2110 - 2170 MHz
LTE-FDD B28	703 - 748 MHz	758 - 803 MHz
LTE-FDD B66	1710 - 1780 MHz	2110 - 2180 MHz
LTE-TDD B38	2570 - 2620 MHz	2570 - 2620 MHz
LTE-TDD B40	2300 - 2400 MHz	2300 - 2400 MHz



LTE-TDD B41 2535 - 265	55 MHz 2535 - 2655 M	Hz

6.2 TX Power and RX Sensitivity

Table 6-2 N728-LA RF transmitting power

Band	Max power	Min. power
850	33 dBm±2 dB	5 dBm±5 dB
EGSM900	33 dBm±2 dB	5 dBm±5 dB
DCS1800	30 dBm±2 dB	0 dBm±5 dB
1900	30 dBm±2 dB	0 dBm±5 dB
WCDMA B1	24 dBm +1/-3 dB	< -50 dBm
WCDMA B2	24 dBm +1/-3 dB	< -50 dBm
WCDMA B4	24 dBm +1/-3 dB	< -50 dBm
WCDMA B5	24 dBm +1/-3 dB	< -50 dBm
WCDMA B8	24 dBm +1/-3 dB	< -50 dBm
LTE-FDD B1	23 dBm±2 dB	< -39 dBm
LTE-FDD B2	23 dBm±2 dB	< -39 dBm
LTE-FDD B1	23 dBm±2 dB	< -39 dBm
LTE-FDD B4	23 dBm±2 dB	< -39 dBm
LTE-FDD B5	23 dBm±2 dB	< -39 dBm
LTE-FDD B7	23 dBm±2 dB	< -39 dBm
LTE-FDD B8	23 dBm±2 dB	< -39 dBm
LTE-FDD B10	23 dBm±2 dB	< -39 dBm
LTE-FDD B28	23 dBm±2 dB	< -39 dBm
LTE-FDD B66	23 dBm±2 dB	< -39 dBm
LTE-TDD B38	23 dBm±2 dB	< -39 dBm
LTE-TDD B40	23 dBm±2 dB	< -39 dBm
LTE-TDD B41	23 dBm±2 dB	< -39 dBm



Table 6-3 N728-LA GSM RX sensitivity

Band	RX sensitivity
GSM900	TBD
EGSM900	TBD
DCS1800	TBD
PCS1900	TBD

Table 6-4 N728-LA WCDMA RX sensitivity

Band	RX sensitivity
WCDMA B1	TBD
WCDMA B2	TBD
WCDMA B4	TBD
WCDMA B5	TBD
WCDMA B8	TBD

Table 6-5 N728-LA LTE RX sensitivity

Band	RX sensitivity	Duplex mode
LTE-FDD B1	TBD	FDD
LTE-FDD B2	TBD	FDD
LTE-FDD B3	TBD	FDD
LTE-FDD B4	TBD	FDD
LTE-FDD B5	TBD	FDD
LTE-FDD B7	TBD	FDD
LTE-FDD B8	TBD	FDD
LTE-FDD B10	TBD	FDD
LTE-FDD B28	TBD	FDD
LTE-FDD B66	TBD	FDD
LTE-TDD B38	TBD	TDD
LTE-TDD B40	TBD	TDD
LTE-TDD B41	TBD	TDD



6.3 GNSS Technical Parameters

Table 6-6 GNSS technical parameters

Parameter	Notice
GPS L1 operating frequency	1575.42±1.023 MHz
BDS operating frequency	1559.1 - 1563.1 MHz
Tracking sensitivity	-146 dBm
Acquisition sensitivity	-157 dBm
Positioning precision (open space)	< 3 m (CEP50)
Hot start (open space)	< 3s
Cold start (open space)	< 40s
Update frequency	< 10 Hz
GNSS data type	NMEA-0183
GNSS antenna type	Passive/active antenna



The preceding indexes are test data in a laboratory environment. The test results of LTE (Cat 4) in a bandwidth of 10 MHz will have a certain deviation due to the influence of the network environment.



7 Considerations for N728-LA Module Usage

When using an LA module for system design, it is important to retest all RF indicators based on the entire system to ensure they meet the required specifications.

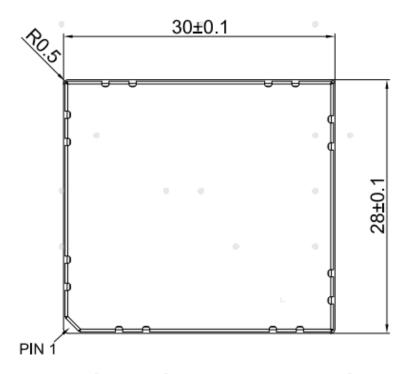


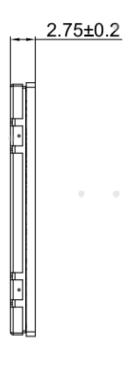
8 Mechanical Characteristics

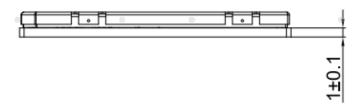
This chapter describes mechanical characteristics of the N728-LA module.

8.1 Dimensions

Figure 8-1 N728-LA top and side view dimensions (unit: mm)









8.2 Labeling

The label information is laser carved on the cover. The following figure shows the label of N728-LA.





- The picture above is only for reference.
- The material and surface finishing must comply with RoHS directives.

8.3 Packaging

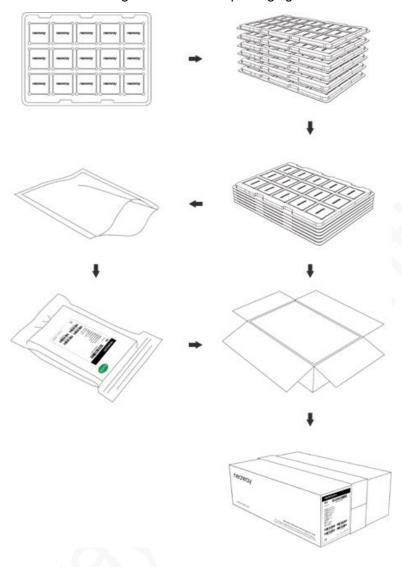
N728-LA adopts the SMD reflow soldering process for electronics assembly. The modules are delivered in trays, which are packed in vacuumed moisture-proof aluminium foil bag. To ensure the dryness of the product and prolong their service life, the bag also holds desiccant and a humidity indicator card.

8.3.1 Tray

Neoway modules are delivered on trays as shown below:



Figure 8-2 N728-LA packaging





The above figure is for reference only. For authentic appearance, please refer to the module that you receive from Neoway.

8.3.2 Moisture Sensitivity Level



N728-LA is a level 3 moisture-sensitive electronic element, in compliance IPC/ JEDEC J-STD-020 standard.

After unpacking, avoid leaving the module exposed to air for too long. If exposed to air for a prolonged period, the module could become damp, increasing the risk of damage during reflow soldering or laboratory soldering. Bake it before mounting the module. The baking conditions depend on the moisture degree. It is recommended to bake the module at temperatures higher than 90 degrees for more than 12 hours. In addition, since the package tray is made of non-high temperature resistant material, do not bake modules with the package tray directly.



9 Mounting N728-LA onto Application Board

The N728-LA module is assembled using the 100-pin LGA package and SMT soldering method.

9.1 PCB Package



To ensure proper operation of the module, only GND via-holes and copper pouring are allowed within the shaded area "\(\begin{align*} \)" of the PCB package.

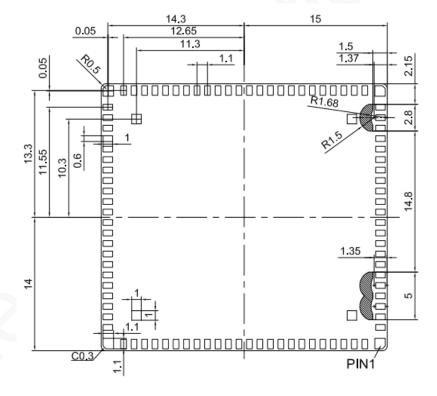


Figure 9-1 Bottom view of N728-LA PCB package (unit: mm)

9.2 Stencil

It is recommended to use stencil thickness of at least 0.15 mm to 0.20 mm (0.18 mm recommended), which can be adjusted as per the actual SMT situation.



9.3 Solder Paste

The thickness of solder paste and the flatness of PCB are essential for the production yield.

It is recommended to use the same kind of leaded solder paste used during the production process of Neoway.

- The melting point of the leaded solder paste is 35°C lower than that of the lead-free solder paste, and the temperature in the reflow process parameters is also lower than that of the lead-free solder paste. Therefore, the soldering time is shorter accordingly, which easily causes a false solder because LGA in the module is in a semi-melted state during the secondary reflow.
- When using only solder pastes with lead, please ensure that the time above 220°C (reflow temperature) exceeds 45 seconds and the peak temperature does not exceed 240°C.

9.4 Oven Temperature Profile



Neoway will not provide warranties for heat-responsive element abnormalities caused by improper temperature control.

If the PCB is large, it is important to avoid bending of the printed circuit material during an SMT process. So a bending prevention tool must be placed on the bottom of the printed circuit board. It is recommended to use loading tools during the SMT and reflow soldering process to avoid poor solder joint caused by PCB bending.

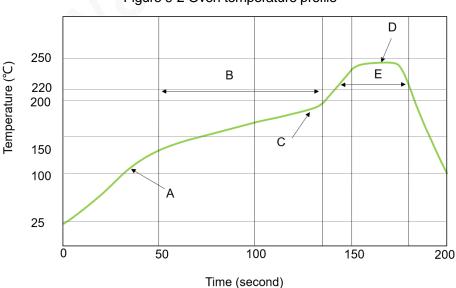


Figure 9-2 Oven temperature profile



Technical parameters:

Ramp up rate: 1 to 4°C/sec

• Ramp down rate: -3 to -1°C/sec

Soaking zone: 150 - 180°C, Time: 60 - 100s

Reflow zone: >220°C, Time: 40 - 90s

Peak temperature: 235 - 245°C

For information about cautions in storage and mounting, refer to Neoway_Reflow_Soldering_Guidelines_For_Surface-Mounted_Modules.

When manually removing a module from your application PCB board, it is important to use heat guns with large openings. Adjust the temperature to about 245°C (depending on the type of solder paste used) and heat the module until the solder paste melts. Use tweezers to remove the module, being careful not to shake it at high temperatures. Shaking the module may cause components inside to become misplaced.



A Abbreviations

Abbreviation	Full name
AI	Analog Input
AO	Analog Output
ARM	Advanced RISC Machine
bps	Bits per Second
CCC	China Compulsory Certification
CS	Chip Select
CTS	Clear to Send
DC	Direct Current
DCS	Digital Cellular System
DI	Digital Input
DL	Downlink
DO	Digital Output
DRX	Discontinuous Reception
EGSM	Enhanced GSM
ESD	Electronic Static Discharge
ESR	Equivalent Series Resistance
EVK	Evaluation Kit
FDD	Frequency Division Duplexing
GNSS	Global Navigation Satellite System
GPIO	General Purpose Input Output
3GPP	3rd Generation Partnership Project
GPRS	General Packet Radio Service
GSM	Global System for Mobile Communications
I2C	Inter-Integrated Circuit
Ю	Input/Output
LCC	Leadless Chip Carriers
LED	Light Emitting Diode



LGA	Land Grid Array
LTE	Long Term Evolution
MCLK	Main Clock
MCU	Microcontroller Unit
PCB	Printed Circuit Board
PWM	Pulse Width Modulation
RAM	Random Access Memory
RF	Radio Frequency
ROM	Read-only Memory
SDIO	Secure Digital Input Output
SPI	Serial Peripheral Interface
TDD	Time Division Duplex
UART	Universal Asynchronous Receiver-Transmitter
UL	Uplink
USB	Universal Serial Bus
USIM	Universal Subscriber Identity Module
VBAT	Battery Voltage
WiFi	Wireless Fidelity
WCDMA	Wide-band Code Division Multiple Access
WLAN	Wireless Local Area Network